High Current Surface Mount PNP Silicon Switching Transistor for Load Management in **Portable Applications**

Features

• Pb-Free Package is Available

MAXIMUM RATINGS ($T_A = 25^{\circ}C$)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	-30	Vdc
Collector-Base Voltage	V _{CBO}	-50	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous	۱ _C	-1.0	Adc
Collector Current – Peak	I _{CM}	-2.0	А
Electrostatic Discharge	ESD	HBM Class 3 MM Class C	

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above $25^{\circ}C$	P _D (Note 1)	540 4.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	230	°C/W
Total Device Dissipation $T_A = 25^{\circ}C$ Derate above $25^{\circ}C$	P _D (Note 2)	925 7.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	135	°C/W
Total Device Dissipation (Single Pulse < 10 s)	P _{Dsingle} (Note 2) (Note 3)	1.3	W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-4 @ Minimum Pad

2. FR-4 @ 1.0 X 1.0 inch Pad

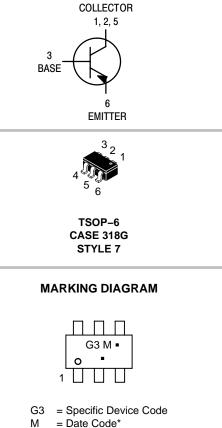
3. ref: Figure 8



ON Semiconductor®

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30 VOLTS, 2.0 AMPS PNP TRANSISTOR



= Pb-Free Package

(Note: Microdot may be in either location) *Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

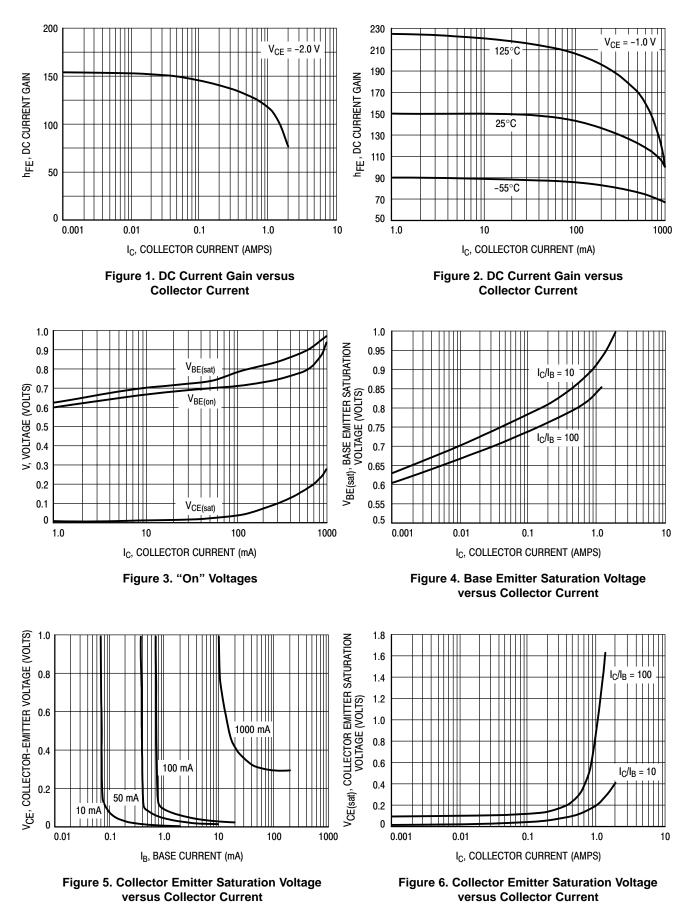
Device	Package	Shipping [†]
MMBT6589T1	TSOP-6	3000/Tape & Reel
MMBT6589T1G	TSOP–6 (Pb–Free)	3000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25° C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				•
Collector – Emitter Breakdown Voltage $(I_C = -10 \text{ mAdc}, I_B = 0)$	V _(BR) CEO	-30	_	Vdc
Collector – Base Breakdown Voltage $(I_C = -0.1 \text{ mAdc}, I_E = 0)$	V _{(BR)CBO}	-50	_	Vdc
Emitter – Base Breakdown Voltage ($I_E = -0.1 \text{ mAdc}, I_C = 0$)	V _{(BR)EBO}	-5.0	_	Vdc
Collector Cutoff Current ($V_{CB} = -30$ Vdc, $I_E = 0$)	I _{CBO}	-	-0.1	μAdc
Collector–Emitter Cutoff Current (V _{CES} = -30 Vdc)	I _{CES}	-	-0.1	μAdc
Emitter Cutoff Current (V _{EB} = -4.0 Vdc)	I _{EBO}	-	-0.1	μAdc
ON CHARACTERISTICS				
DC Current Gain (Note 4) (Figure 1) ($I_C = -1.0 \text{ mA}, V_{CE} = -2.0 \text{ V}$) ($I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V}$) ($I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}$) ($I_C = 2.0 \text{ A}, V_{CE} = -2.0 \text{ V}$)	h _{FE}	100 100 80 40	 300 	
Collector – Emitter Saturation Voltage (Note 4) (Figure 3) ($I_C = -0.5 \text{ A}, I_B = -0.05 \text{ A}$) ($I_C = -1.0 \text{ A}, I_B = 0.1 \text{ A}$) ($I_C = -2.0 \text{ A}, I_B = -0.2 \text{ A}$)	V _{CE(sat)}		-0.25 -0.30 -0.65	V
Base – Emitter Saturation Voltage (Note 4) (Figure 2) $(I_C = -1.0 \text{ A}, I_B = -0.1 \text{ A})$	V _{BE(sat)}	-	-1.2	V
Base – Emitter Turn–on Voltage (Note 4) ($I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}$)	V _{BE(on)}	-	-1.1	V
Cutoff Frequency ($I_C = -100 \text{ mA}, V_{CE} = -5.0 \text{ V}, f = 100 \text{ MHz}$)	f _T	100	_	MHz
Output Capacitance (V _{CB} = -5.0 V, f = 1.0 MHz)	Cobo	-	20	pF

4. Pulsed Condition: Pulse Width = 300 μ sec, Duty Cycle \leq 2%



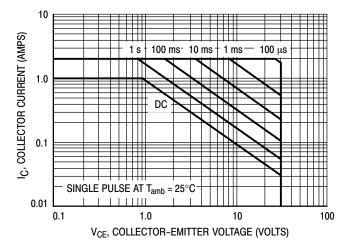


Figure 7. Safe Operating Area

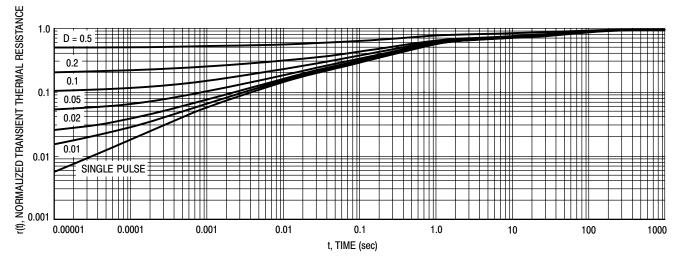


Figure 8. Normalized Thermal Response

TSOP-6 3.00x1.50x0.90, 0.95P **CASE 318G ISSUE W** DATE 26 FEB 2024 NDTES D DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018. 1. CONTROLLING DIMENSION: MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM 2. З. 6 5 4 LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. MATERIAL. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H. PIN 1 INDICATOR MUST BE LOCATED IN THE INDICATED ZONE Ē1 NOTE 5 1 3 MILLIMETERS H DIM MIN NΠΜ MAX e -2 GAUGE PLANE 0.90 1.00 1.10 А TOP VIEW A1 0.01 0.06 0.10 0.80 0.90 1.00 Α2 -A2 0.25 0.38 0.50 b SEATING PLANE Μ Ċ 0.10 0.18 0.26 С 0.05 C 3.00 DETAIL Z D 2.90 3.10 SCALE 3:1 F 2.50 A1-2.75 3.00 SIDE VIEW PLANE Ε1 1.30 1.50 1.70 0.85 0.95 1.05 е 0.20 0.40 DETAIL Z L 0.60 L2 0.25 BSC М 0° 10° 6X --0.60 END VIEW 6X -0.95 3.20 1 -0.95 PITCH RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download th e EN Semiconductor Soldering and Mounting Techniques Reference manual, SELDERRM/D.

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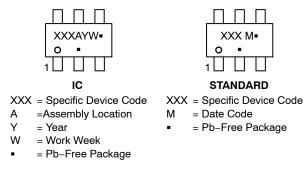
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DATE 26 FEB 2024

GENERIC MARKING DIAGRAM*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 2: PIN 1. EMITTER 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. BASE 2 6. COLLECTOR 2	STYLE 3: PIN 1. ENABLE 2. N/C 3. R BOOST 4. Vz 5. V in 6. V out	STYLE 4: PIN 1. N/C 2. V in 3. NOT USED 4. GROUND 5. ENABLE 6. LOAD	STYLE 5: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 6: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR
STYLE 7: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. N/C 5. COLLECTOR 6. EMITTER	STYLE 8: PIN 1. Vbus 2. D(in) 3. D(in)+ 4. D(out)+ 5. D(out) 6. GND	STYLE 9: PIN 1. LOW VOLTAGE GATE 2. DRAIN 3. SOURCE 4. DRAIN 5. DRAIN 6. HIGH VOLTAGE GATE	2. GND 3. D(OUT)– 4. D(IN)– 5. VBUS	STYLE 11: PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1/GATE 2	STYLE 12: PIN 1. I/O 2. GROUND 3. I/O 4. I/O 5. VCC 6. I/O
STYLE 13: PIN 1. GATE 1 2. SOURCE 2 3. GATE 2 4. DRAIN 2 5. SOURCE 1 6. DRAIN 1	STYLE 14: PIN 1. ANODE 2. SOURCE 3. GATE 4. CATHODE/DRAIN 5. CATHODE/DRAIN 6. CATHODE/DRAIN		LE 16: N 1. ANODE/CATHODE 2. BASE 3. EMITTER 4. COLLECTOR 5. ANODE 6. CATHODE	STYLE 17: PIN 1. EMITTER 2. BASE 3. ANODE/CATHODE 4. ANODE 5. CATHODE 6. COLLECTOR	

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